

### Product Innovation From





## Dual Power Operational Amplifiers



### **FEATURES**

- Rohs compliant
- LOW COST
- WIDE BANDWIDTH 1.1 Mhz
- HIGH OUTPUT CURRENT 2.5A (Combined)
- WIDE COMMON MODE RANGE Includes negative supply
- WIDE SUPPLY VOLTAGE RANGE Single supply: 5V to 40V
   Split supplies: ± 2.5V to ± 20V
- LOW QUIESCIENT CURRENT
- VERY LOW DISTORTION

#### **APPLICATIONS**

- HALF AND FULL BRIDGE MOTOR DRIVERS
- AUDIO POWER AMPLIFIER
- IDEAL FOR SINGLE SUPPLY SYSTEMS
   5V Peripherals, 12V Automotive, 28V Avionic

#### PACKAGING OPTIONS

- 7 TO-220 Plastic Package (PA75CD)
- 7 TO-220 with Staggered Lead Form (PA75CX)
- 7 DDPAK Surface Mount Package (PA75CC)

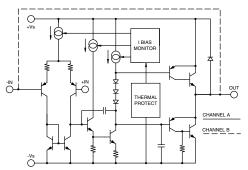
#### **DESCRIPTION**

The amplifier design consists of dual power op amp on a single monolithic die. Side B of the dual monolithic is configured as a unity gain buffer to increase the current capability of the master side A. The use of two PA75 amplifiers provides a cost-effective solution to applications where multiple amplifiers are required or a bridge configuration is needed. Very low harmonic distortion of .02% THD and low  $\rm I_Q$  makes the PA75 a good solution for power audio applications.

The PA75 is available in three standard package designs. The surface mount version of the PA75, the PA75CC, is an industry standard non-hermetic plastic 7-pin DDPAK. The through hole version of the PA75, the PA75CD and PA75CX, are industry standard non-hermetic plastic 7-pin TO-220 packages. The PA75CX is staggered lead formed and offers standard 100 mil spacing. This allows for easier PC board layout. (Please refer to the CX lead form package drawing for dimension of the PA75CX).

The monolithic amplifier is directly attached to the metal tabs of the PA75CC, PA75CD, and PA75CX. The metal tabs of the packages are directly tied to -Vs.

### **EQUIVALENT SCHEMATIC** ONE CHANNEL

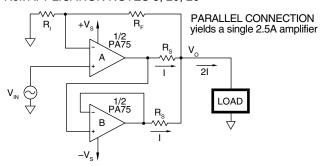




7 PIN TO220 STAGGERED LEADS PACKAGE STYLE CX 7 PIN TO220 PACKAGE STYLE CD

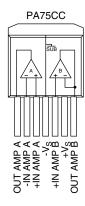
#### TYPICAL APPLICATION

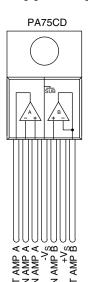
Ref: APPLICATION NOTES 8, 20, 26

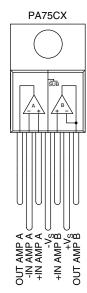


Combining the power op amp (master channel A) and the unity gain buffer (slave channel B) in a parallel connection yields a single 2.5A amplifier. RI and RF can set up channel A for the required gain for the overall circuit. Small values of  $R_{\rm S}$  (sense resistors) are used on the outputs to improve current sharing characteristics. The master amplifier can be configured in inverting or non-inverting gain configurations.

# EXTERNAL CONNECTIONS













-40°C to 125°C

### **ABSOLUTE MAXIMUM RATINGS**

SUPPLY VOLTAGE, total 5V to 40V **OUTPUT CURRENT** SOA POWER DISSIPATION, internal, (per amplifier) 19.5W 28.6W POWER DISSIPATION, internal (both amplifiers) ±V<sub>S</sub> +V<sub>S</sub>, -V<sub>S</sub>-0.5V 150°C INPUT VOLTAGE, differential INPUT VOLTAGE, common mode JUNCTION TEMPERATURE, max1 TEMPERATURE, pin solder—10 sec max 220°C TEMPERATURE RANGE, storage -55°C to 150°C OPERATING TEMPERATURE RANGE, case

#### **SPECIFICATIONS**

PARAMETER	TEST CONDITIONS 2	MIN	TYP	MAX	UNITS
INPUT OFFSET VOLTAGE, initial OFFSET VOLTAGE, vs. temperature BIAS CURRENT, initial COMMON MODE RANGE COMMON MODE REJECTION, DC POWER SUPPLY REJECTION CHANNEL SEPARATION INPUT NOISE VOLTAGE	Full temperature range   Full temperature range   Full temperature range   Full temperature range   I <sub>OUT</sub> = $500\text{mA}$ , $f = 1\text{kHz}$ R <sub>S</sub> = $100\Omega$ , $f = 1$ to $100\text{kHz}$	-V <sub>s</sub> 60 60 50	1 20 100 90 90 68 22	15 500 +V <sub>S</sub> -1.3	mV μV/°C nA V dB dB dB nV/√Hz
GAIN OPEN LOOP GAIN GAIN BANDWIDTH PRODUCT PHASE MARGIN POWER BANDWIDTH	Full temperature range $A_V = 40 dB$ Full temperature range, $R_L = 2 K \Omega$ , $C_L = 100 pF$ $V_{O(P-P)} = 28 V$	89 0.9	100 1.4 65 13.6		dB MHz ° kHz
OUTPUT CURRENT, peak SLEW RATE VOLTAGE SWING VOLTAGE SWING HARMONIC DISTORTION	Full Temperature Range, $I_O = 100 \text{mA}$ Full Temperature Range, $I_O = 1 \text{A}$ $A_V = 1$ , $R_2 = 50 \Omega$ , $V_O = .5 V_{\text{RMS}}$ , $f = 1 \text{kHz}$	1  V <sub>S</sub>   - 1.1  V <sub>S</sub>   - 1.8	1.4  V <sub>S</sub>  8  V <sub>S</sub>   - 1.4 .02	1.5	A V/µs V V %
POWER SUPPLY VOLTAGE, V <sub>SS</sub> <sup>3</sup> CURRENT, quiescent, total		5	30 8	40 10	V mA
THERMAL RESISTANCE,DC junction to case (single) RESISTANCE,AC junction to case (single) RESISTANCE,DC junction to case (both) RESISTANCE,AC junction to case (both) RESISTANCE,junction to air (CD,CX) RESISTANCE,junction to air (CC) <sup>4</sup> TEMPERATURE RANGE,case	Meets full range specifications	<b>-2</b> 5	5.84 4.38 3.97 2.98 60 27	6.42 4.81 4.36 3.27	°C/W °C/W °C/W °C/W °C/W °C/W °C/C

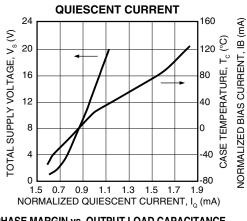
- NOTES: 1. Long term operation at the maximum junction temperature will result in reduced product life. Derate internal power dissipation to achieve high MTTF.

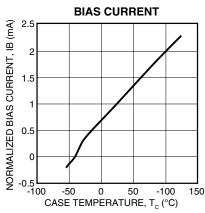
  - Unless otherwise noted, the following conditions apply: ±V<sub>S</sub> = ±15V, T<sub>C</sub> = 25°C.
     +V<sub>S</sub> and -V<sub>S</sub> denote the positive and negative supply rail respectively. V<sub>SS</sub> denotes the total rail-to-rail supply voltage.
  - 4. Heat tab attached to 3/32" FR-4 board with 2oz. copper. Topside copper area (heat tab directly attached) = 1000 sq. mm, backside copper area = 2500 sq. mm, board area = 2500 sq. mm.

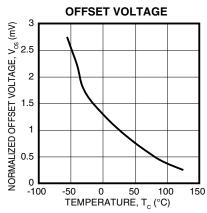
2 PA75U



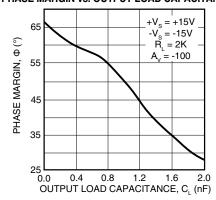


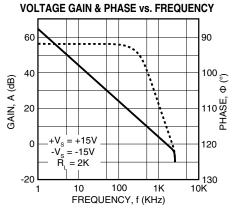


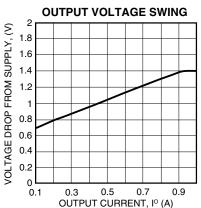


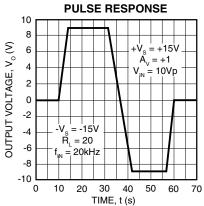


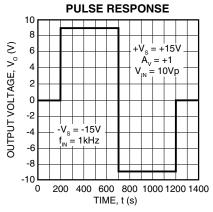
### PHASE MARGIN vs. OUTPUT LOAD CAPACITANCE











PA75U 3



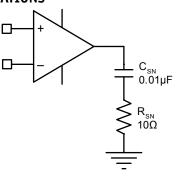


#### **GENERAL**

Please read Application Note 1 "General Operating Considerations" which covers stability, supplies, heatsinking, mounting, SOA interpretation, and specification interpretation. Visit www. Cirrus.com for design tools that help automate tasks such as calculations for stability, internal power dissipation, heatsink selection; Apex Precision Power's complete Application Notes library; Technical Seminar Workbook; and Evaluation Kits.

#### STABILITY CONSIDERATIONS

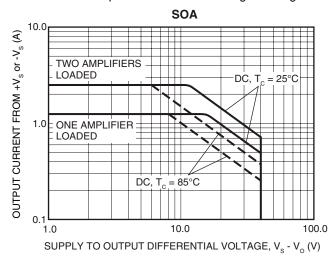
All monolithic power op amps use output stage topologies that present special stability problems. This is primarily due to noncomplementary (both devices are NPN) output stages with a mismatch in gain and phase response for different polarities of output current. It is dif-



ficult for the op amp manufacturer to optimize compensation for all operating conditions. For applications with load current exceeding 300ma, oscillation may appear. The oscillation may occur only with the output voltage swing at the negative or positive half cycle. Under most operating and load conditions acceptable stability can be achieved by providing a series RC snubber network connected from the output to ground. The recommended component values of the of the network are,  $R_{\rm SN}=10\Omega$  and  $C_{\rm SN}=0.01\mu F$ . Please refer to Application Note 1 for further details.

#### SAFE OPERATING AREA (SOA)

The SOA curves combine the effect of all limits for this power op amp. For a given application, the direction and magnitude of the output current should be calculated or measured and checked against the SOA curves. This is simple for resistive loads but more complex for reactive and EMF generating loads.



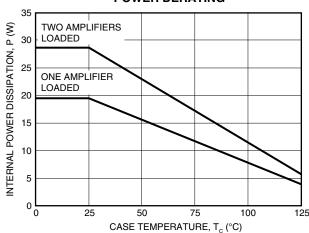
#### THERMAL CONSIDERATIONS

The PA75CD and CX have a large exposed copper heat tab to which the monolithic is directly attached. The PA75CD and CX may require a thermal washer, which is electrically insulating since the tab is directly tied to -VS. This can result in a thermal impedance RCS of up to 1°C/W or greater.

The PA75CC has a large exposed integrated copper heatslug to which the monolithic is directly attached. The solder connection of the heatslug to a minimum of 1 square inch foil area of the printed circuit board will result in thermal performance of 25°C/W junction to air rating of the PA75CC. Solder connection to an area of 1 to 2 square inches of foil is required for minimal power applications

Where the PA75CC is used in higher power applications, it is necessary to use surface mount techniques of heatsinking. Surface mount techniques include the use of a surface mount fan in combination with a surface mount heatsink on the backside of the FR4/ PC board with through hole thermal vias. Other highly thermal conductive substrate board materials are available for maximum heat sinking.

#### **POWER DERATING**



#### MOUNTING PRECAUTIONS

- Always use a heat sink. Even unloaded the PA75 can dissipate up to .4 watts.
- 2. Avoid bending the leads. Such action can lead to internal damage.
- Always fasten the tab of the CD and CX package to the heat sink before the leads are soldered to fixed terminals.
- 4. Strain relief must be provided if there is any probability of axial stress to the leads.

4 PA75U